

Amendments to the Claims

This listing of claims will replace all prior listings of claims in the application.

Listing of Claims

1.-4. (Canceled)

5. (Currently Amended) An electroless copper plating method according to ~~Claim 1~~Claim 6, wherein the first reducing agent is glyoxylic acid, the second reducing agent is hypophosphorous acid and the stabilizer to inhibit copper deposition is 2,2'-bipyridyl.

6. (New) An electroless copper plating method comprising the steps of:

preparing a pretreatment agent by reacting or mixing a noble metal compound and a silane coupling agent having a functional group with metal-capturing capability;

pretreating a mirror surface having a surface roughness of less than 10 nm with the pretreatment agent prior to electroless copper plating;

performing electroless copper plating on the pretreated mirror surface with an electroless copper plating solution comprising a first reducing agent, hypophosphorous acid or a hypophosphite as a second reducing agent and a stabilizer for inhibiting copper deposition; and

forming a thin film having a thickness of no more than 500 nm on the pretreated mirror surface by the electroless copper plating.